

Supplemental Information

This notice describes the differences between the updated version and its previous version of the IDT82V3155 Data Sheet. It helps readers to identify the changes when the data sheet is upgraded.

Revision History

Revision Date	PCN Number (if applicable)	Changed Items
November 18, 2004	-	Item 2 - 1

Changed Items

November 18, 2004

Item 2: Added green package option (page 1, 30)

Item 1: Corrected an error description on the State Control Circuit (page 10, 3rd paragraph of the left column)

Old: "When changing the operating mode, the TIE control block is enabled/disabled automatically by the state control circuit as shown in [Figure - 3](#), except for the changes from Normal (S1) to Auto-Holdover (S2), and from Auto-Holdover (S2), Holdover (S3) and Short Time Holdover (S4) to Normal (S1). During these four changes, the TIE control block can be enabled or disabled, depending on the logic level on the TIE_en pin."

New: "When the operating mode is changed from one to another, the TIE control block is automatically disabled as shown in [Figure - 3](#), except the changes from Holdover (S3) or Auto-Holdover (S2) to Normal (S1). In the case of changing from S3 or S2 to S1, the TIE control block is enabled or disabled by the TIE_en pin."

IMPORTANT NOTICE AND DISCLAIMER

RENESAS ELECTRONICS CORPORATION AND ITS SUBSIDIARIES ("RENESAS") PROVIDES TECHNICAL SPECIFICATIONS AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS OR IMPLIED, INCLUDING, WITHOUT LIMITATION, ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT OF THIRD-PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for developers who are designing with Renesas products. You are solely responsible for (1) selecting the appropriate products for your application, (2) designing, validating, and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. Renesas grants you permission to use these resources only to develop an application that uses Renesas products. Other reproduction or use of these resources is strictly prohibited. No license is granted to any other Renesas intellectual property or to any third-party intellectual property. Renesas disclaims responsibility for, and you will fully indemnify Renesas and its representatives against, any claims, damages, costs, losses, or liabilities arising from your use of these resources. Renesas' products are provided only subject to Renesas' Terms and Conditions of Sale or other applicable terms agreed to in writing. No use of any Renesas resources expands or otherwise alters any applicable warranties or warranty disclaimers for these products.

(Disclaimer Rev.1.01 Jan 2024)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit www.renesas.com/contact-us/.

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.